On behalf of 2020 InterPACK organizing committee, we are pleased to announce that a student poster competition will be held during 2020 InterPACK (October 27-29, Hilton Anaheim, Anaheim, CA).

The Industry, Academia and National Lab Poster Session during InterPACK will be open to all students. It will provide a great opportunity for student attendees to showcase their research, and collect feedback from professionals and experts in the area of electronics and photonics packaging in an interactive way. This is also a networking opportunity for the students who have an interest in distributing their resumes and connecting with professionals from industry, academia and national labs.

Each student poster in this competition will be judged by experts in the area of electronics and photonics packaging on the following aspects: originality, technical quality, completeness, clarity, and communications and interactions during the poster session. Three top student posters will be awarded '**Nasser Grayeli Best Student Poster Award**' and '**Nasser Grayeli Outstanding Student Poster Award**' in honor of Dr. Nasser Grayeli, and a limited of number of student posters will be awarded with InterPACK2020 registration wavier that will be presented during the 2020 InterPACK Awards Luncheon. The InterPACK registration fees will be reimbursed for one student author who leads and presents his/her corresponding poster from each of these limited number of winning student posters (one student author only for each poster) after the InterPACK Conference.

Submission and criteria:

- You must register for 2020 InterPACK as a graduate or undergraduate student attendee and pay the corresponding registration fee. The reimbursement of the registration fee for the three student winners of this competition will happen after InterPACK, and will be handled by ASME.
- Submit a poster abstract to the InterPACK Track 'Industry, Academia and National Lab Posters" by July 16, 2020. This poster abstract can be similar to the abstract you submitted for a technical paper or technical presentation-only contribution. After submitting your abstract, please indicate your interest in being considered for the Student Poster Competition by emailing track chairs of Chen and Kyle (chengchen@fb.com, gluesenkampk@ornl.gov).
- In order to qualify for this student poster competition award and future reimbursement of the registration fee, the student should be the first author of the poster, and present the poster onsite during the poster session at InterPACK.
- Bring in your poster and present it during the poster session of InterPACK. The specific date, time and location of this session at the Hilton Anaheim will be announced later.
- Students are encouraged to submit their resume to ipakres@asme.org. These resumes will be provided by ASME to all institutions that are interested in potentially hiring these students.

Key dates:

- Abstract submission deadline to the Track of "Industry, Academia and National Lab Posters" at the 2019 InterPACK: **July 16th, 2020.**
- Poster presentation during poster session at InterPACK: one day during Oct. 27-29th, 2020 (exact date and time to be announced later)
- Award announcement: 2020 InterPACK Awards Luncheon.

For questions or inquiries, please contact poster track chairs Kyle Gluesenkamp (gluesenkampk@ornl.gov) and Cheng Chen (chengchen@fb.com).